

### ABSTRACT

The present invention provides an aqueous composition useful for polishing silica and silicon nitride on a semiconductor wafer comprising by weight percent 0.001 to 1 phthalic acid and salts thereof, 0.001 to 1 quaternary ammonium compound, 0.01 to 5 carboxylic acid polymer, 0.01 to 5 abrasive and balance water.